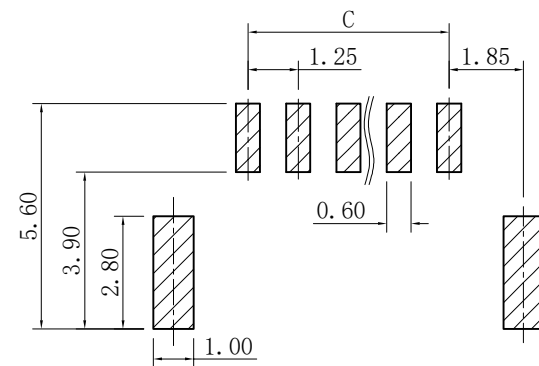
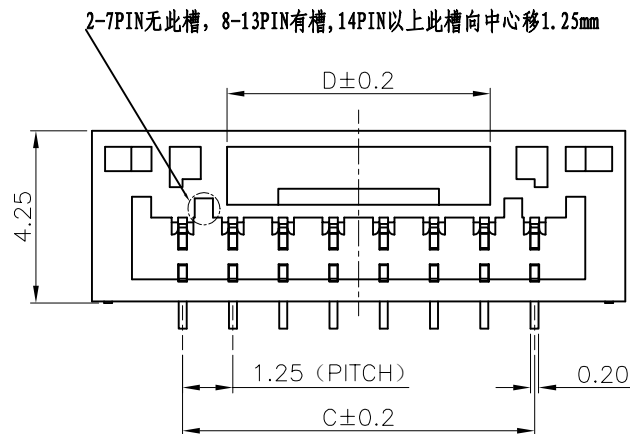


REV.	ECN NO	DESCRIPTION	REVISED	DATE
A		新订图面	KEVIN	2014.6.9
B	20211213068	增加焊片焊锡面积及强度	HELLER	2021.12.13

PIN 数	DIM			
	A	B	C	D
2	5.75	4.95	1.25	2.20
3	7.00	6.20	2.50	3.30
4	8.25	7.45	3.75	4.55
5	9.50	8.70	5.00	5.80
6	10.75	9.95	6.25	7.05
7	12.00	11.20	7.50	8.30
8	13.25	12.45	8.75	9.55
9	14.50	13.70	10.00	10.80
10	15.75	14.95	11.25	12.05
11	17.00	16.20	12.50	13.30
12	18.25	17.45	13.75	14.55
13	19.50	18.70	15.00	15.80
14	20.75	19.95	16.25	17.05
15	22.00	21.20	17.50	18.30
16	23.25	22.45	18.75	19.55
17	24.50	23.70	20.00	20.80
18	25.75	24.95	21.25	22.05
19	27.00	26.20	22.50	23.30
20	28.25	27.45	23.75	24.55

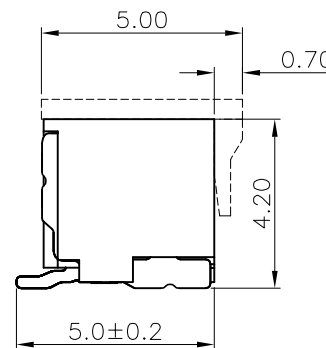
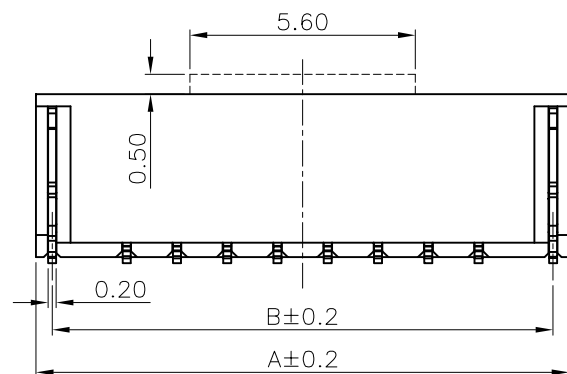


Recommended P.C.Board Layout

Specifications/技术规格:

Current rating: 1A  
 额定电流: 1A  
 Voltage rating: 50V AC,DC  
 额定电压: 50V AC, DC  
 Insulation Resistance: 500MΩ Min.  
 绝缘电阻: 最小500MΩ  
 Dielectric Withstanding: 500V AC 1Min  
 耐电压: 500V AC 1分钟  
 Contact Resistance: 20mΩ Max.  
 接触电阻: 最大20mΩ  
 Operating Temperature: -25°C to +85°C  
 工作温度: -25°C 到85°C

Materials/材料:  
 Contact/Soldering Material: Phos.bronze (Tin plating)  
 接触端子/焊片材料: 磷铜(镀锡)  
 Insulation Material: LCP or PA UL94 V-0  
 绝缘体塑胶材质: LCP 或 PA UL94 V-0



浙江快利电子有限公司  
 Zhejiang Kuaili Electronic Co., Ltd

REV. B UNIT. MM SCALE. 1:1

GENERAL TOLERANCE

X* ± 3*	.XXX: ±0.10
.X* ± 2*	.XX: ±0.15
.XX* ± 1*	.X: ±0.25
.XXX* ± 0.5*	X: ±0.35

DESIGN: HELLER

DATE: 2021.12.13

DWG. NO.

TITLE.

AUDITED:

DATE:

PART NO.

GH-NALT 立贴

APPROVED:

DATE:

KL-GH-NALT